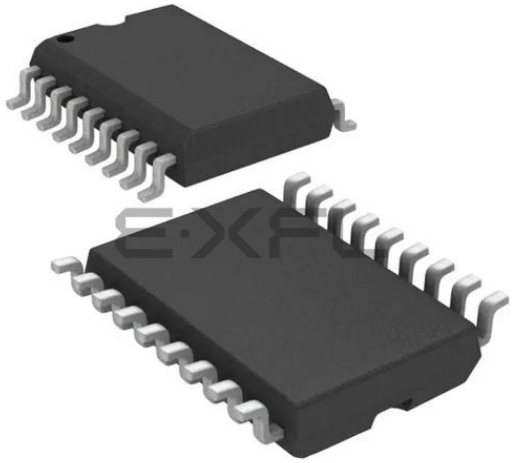

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	Z8
Core Size	8-Bit
Speed	10MHz
Connectivity	-
Peripherals	WDT
Number of I/O	13
Program Memory Size	512B (512 x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	32 x 8
Voltage - Supply (Vcc/Vdd)	3.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z8e00010ssg

GENERAL DESCRIPTION (Continued)

Note: All signals with an overline, "‾", are active Low. For example, B/$\overline{W}$ (WORD is active Low, only); $\overline{B}$/W (BYTE is active Low, only).

Power connections follow conventional descriptions below:

Connection	Circuit	Device
Power	V_{CC}	V_{DD}
Ground	GND	V_{SS}

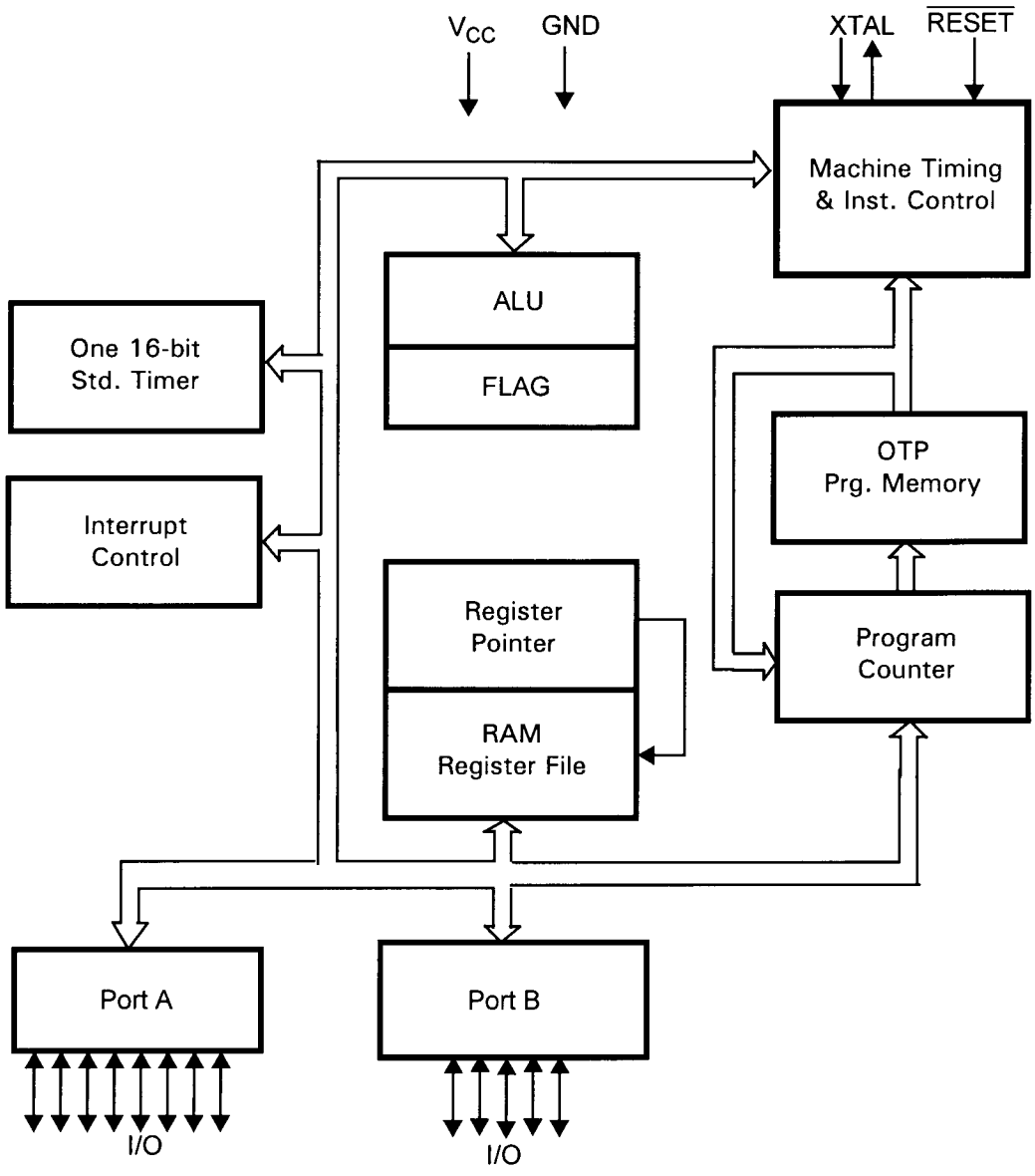


Figure 1. Functional Block Diagram

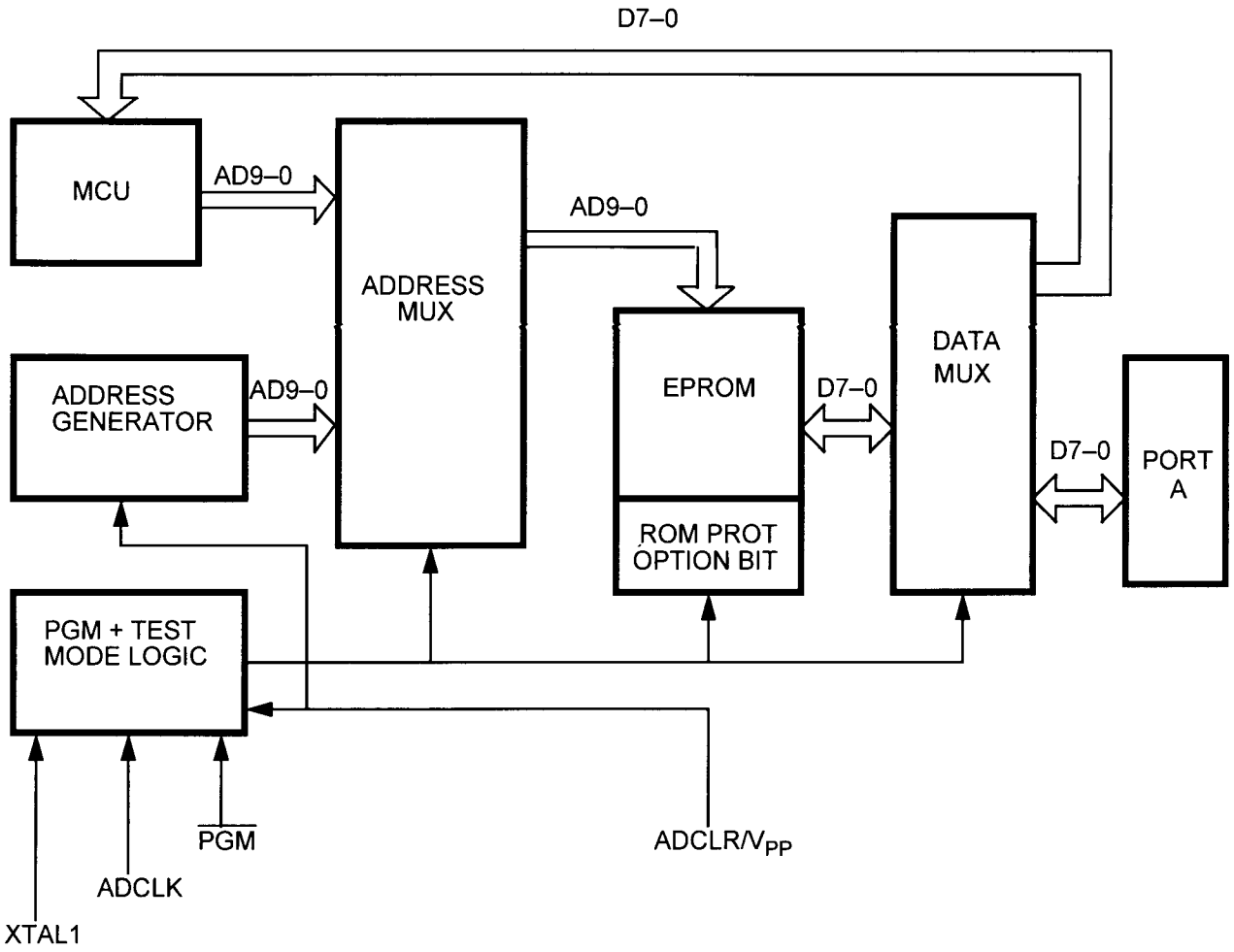


Figure 2. EPROM Programming Mode Block Diagram

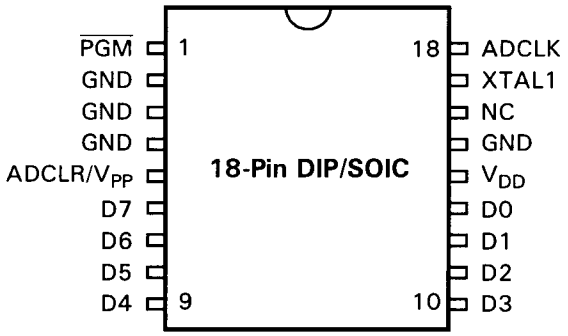


Figure 4. 18-Pin DIP/SOIC Pin Identification; EPROM Programming Mode

Table 2. 18-Pin DIP/SOIC Pin Assignments; EPROM Programmable Mode

EPROM Programming Mode			
Pin #	**Symbol**	**Function**	**Direction**
1	$\overline{PGM}$	Program Mode	Input
2–4	GND	Ground	
5	ADCLR/V_{PP}	Clear Clock/Program Voltage	Input
6–9	D7–D4	Data 7,6,5,4	In/Output
10–13	D3–D0	Data 3,2,1,0	In/Output
14	V_{DD}	Power Supply	
15	GND	Ground	
16	NC	No Connection	
17	XTAL1	1 MHz Clock	Input
18	ADCLK	Address Clock	Input

ABSOLUTE MAXIMUM RATINGS

Parameter	Min	Max	Units	Note
Ambient Temperature under Bias	–40	+105	C	
Storage Temperature	–65	+150	C	
Voltage on any Pin with Respect to V_{SS}	–0.6	+7	V	1
Voltage on V_{DD} Pin with Respect to V_{SS}	–0.3	+7	V	
Voltage on $\overline{RESET}$ Pin with Respect to V_{SS}	–0.6	V_{DD}+1	V	2
Total Power Dissipation		880	mW	
Maximum Allowable Current out of V_{SS}		80	mA	
Maximum Allowable Current into V_{DD}		80	mA	
Maximum Allowable Current into an Input Pin	–600	+600	mA	3
Maximum Allowable Current into an Open-Drain Pin	–600	+600	mA	4
Maximum Allowable Output Current Sunk by Any I/O Pin		25	mA	
Maximum Allowable Output Current Sourced by Any I/O Pin		25	mA	
Maximum Allowable Output Current Sunk by Port A		40	mA	
Maximum Allowable Output Current Sourced by Port A		40	mA	
Maximum Allowable Output Current Sunk by Port B		40	mA	
Maximum Allowable Output Current Sourced by Port B		40	mA	

Notes:
1. Applies to all pins except the $\overline{RESET}$ pin and where otherwise noted.
2. There is no input protection diode from pin to V_{DD}.
3. Excludes XTAL pins.
4. Device pin is not at an output Low state.

Stresses greater than those listed under Absolute Maximum Ratings can cause permanent damage to the device. This rating is a stress rating only. Functional operation of the device at any condition above those indicated in the operational sections of these specifications is not implied. Exposure to absolute maximum rating conditions for an extended period can affect device reliability. Total power dissipation should not exceed 880 mW for the package. Power dissipation is calculated as follows:

$$\text{Total Power Dissipation} = V_{DD} \times [I_{DD} - (\text{sum of } I_{OH})] + \text{sum of } [(V_{DD} - V_{OH}) \times I_{OH}] + \text{sum of } (V_{0L} \times I_{0L})$$

STANDARD TEST CONDITIONS

The characteristics listed below apply for standard test conditions as noted. All voltages are referenced to Ground. Positive current flows into the referenced pin (Figure 7).

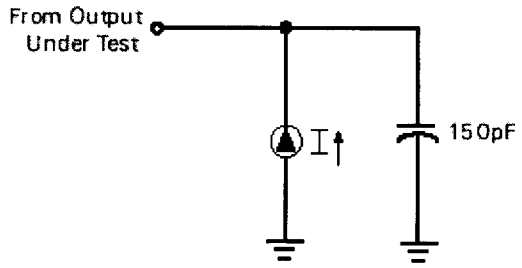


Figure 7. Test Load Diagram

CAPACITANCE

T_A = 25°C, V_{CC} = GND = 0V, f = 1.0 MHz, unmeasured pins returned to GND.

Parameter	Min	Max
Input capacitance	0	12 pF
Output capacitance	0	12 pF
I/O capacitance	0	12 pF

DC ELECTRICAL CHARACTERISTICS

			T_A = 0°C to +70°C					
Sym	Parameter	V_{CC}[1]	Min	Max	Typical @ 25°C[2]	Units	Conditions	Notes
V_{CH}	Clock Input High Voltage	3.5V	$0.7V_{CC}$	V_{CC}+0.3	1.3	V	Driven by External Clock Generator	
		5.5V	$0.7V_{CC}$	V_{CC}+0.3	2.5	V	Driven by External Clock Generator	
V_{CL}	Clock Input Low Voltage	3.5V	V_{SS}–0.3	$0.2V_{CC}$	0.7	V	Driven by External Clock Generator	
		5.5V	V_{SS}–0.3	$0.2V_{CC}$	1.5	V	Driven by External Clock Generator	
V_{IH}	Input High Voltage	3.5V	$0.7V_{CC}$	V_{CC}+0.3	1.3	V		
		5.5V	$0.7V_{CC}$	V_{CC}+0.3	2.5	V		
V_{IL}	Input Low Voltage	3.5V	V_{SS}–0.3	$0.2V_{CC}$	0.7	V		
		5.5V	V_{SS}–0.3	$0.2V_{CC}$	1.5	V		
V_{OH}	Output High Voltage	3.5V	V_{CC}–0.4		3.1	V	I_{OH} = –2.0 mA	
		5.5V	V_{CC}–0.4		4.8	V	I_{OH} = –2.0 mA	
V_{OL1}	Output Low Voltage	3.5V		0.6	0.2	V	I_{OL} = +4.0 mA	
		5.5V		0.4	0.1	V	I_{OL} = +4.0 mA	
V_{OL2}	Output Low Voltage	3.5V		1.2	0.5	V	I_{OL} = +6 mA	
		5.5V		1.2	0.5	V	I_{OL} = +12 mA	
V_{RH}	Reset Input High Voltage	3.5V	$0.5V_{CC}$	V_{CC}	1.1	V		
		5.5V	$0.5V_{CC}$	V_{CC}	2.2	V		
V_{RL}	Reset Input Low Voltage	3.5V	V_{SS}–0.3	$0.2V_{CC}$	0.9	V		
		5.5V	V_{SS}–0.3	$0.2V_{CC}$	1.4	V		
I_{IL}	Input Leakage	3.5V	–1.0	2.0	0.064	µA	V_{IN} = 0V, V_{CC}	
		5.5V	–1.0	2.0	0.064	µA	V_{IN} = 0V, V_{CC}	
I_{OL}	Output Leakage	3.5V	–1.0	2.0	0.114	µA	V_{IN} = 0V, V_{CC}	
		5.5V	–1.0	2.0	0.114	µA	V_{IN} = 0V, V_{CC}	
I_{IR}	Reset Input Current	3.5V	–10	–60	–30	µA		
		5.5V	–20	–180	–100	µA		
I_{CC}	Supply Current	3.5V		2.5	2.0	mA	@ 10 MHz	3,4
		5.5V		6.0	4.0	mA	@ 10 MHz	3,4
I_{CC1}	Standby Current	3.5V		2.0	1.0	mA	Halt Mode V_{IN} = 0V V_{CC}@10 MHz	3,4
		5.5V		6.0	4.0	mA	Halt Mode V_{IN} = 0V V_{CC}@10 MHz	3,4

Sym	Parameter	V_{CC}[1]	T_A = 0°C to +70°C Min	Max	Typical @ 25°C[2]	Units	Conditions	Notes
I_{CC2}	Standby Current	3.5V		500	150	nA	Stop Mode V_{IN} = 0V, V_{CC}	5
		5.5V		500	250	nA	Stop Mode V_{IN} = 0V, V_{CC}	5

Notes:

1. The V_{CC} voltage specification of 3.5 V guarantees 3.5 V and the V_{CC} voltage specification of 5.5 V guarantees 5.0 V ±0.5 V.
2. Typical values are measured at V_{CC} = 3.3V and V_{CC} = 5.0V.
3. All outputs unloaded, I/O pins floating, and all inputs are at V_{CC} or V_{SS} level.
4. CL1 = CL2 = 22 pF.
5. Same as note 3 except inputs at V_{CC}.

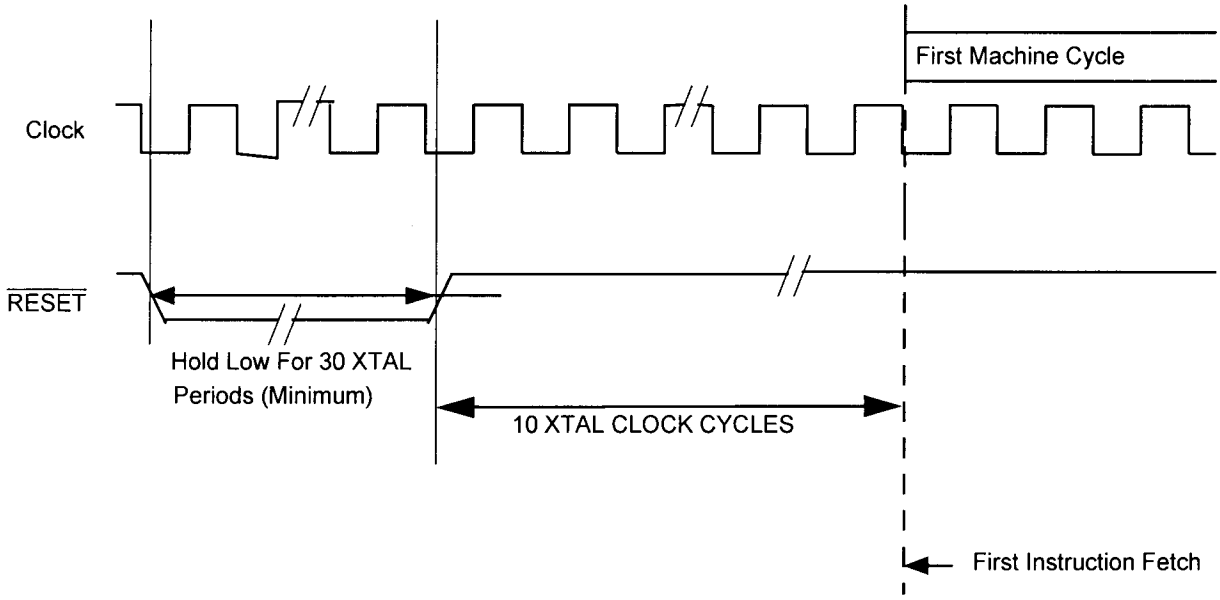


Figure 9. Reset Timing

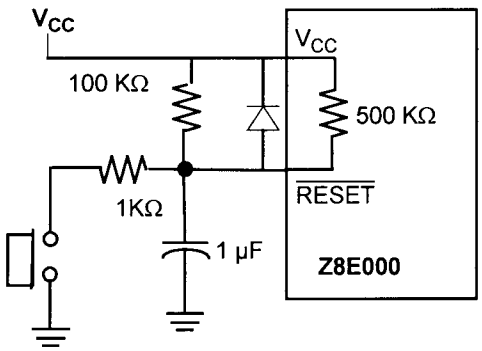


Figure 10. Example of External Power-On Reset Circuit

Z8E000 WATCH-DOG TIMER (WDT) (Continued)

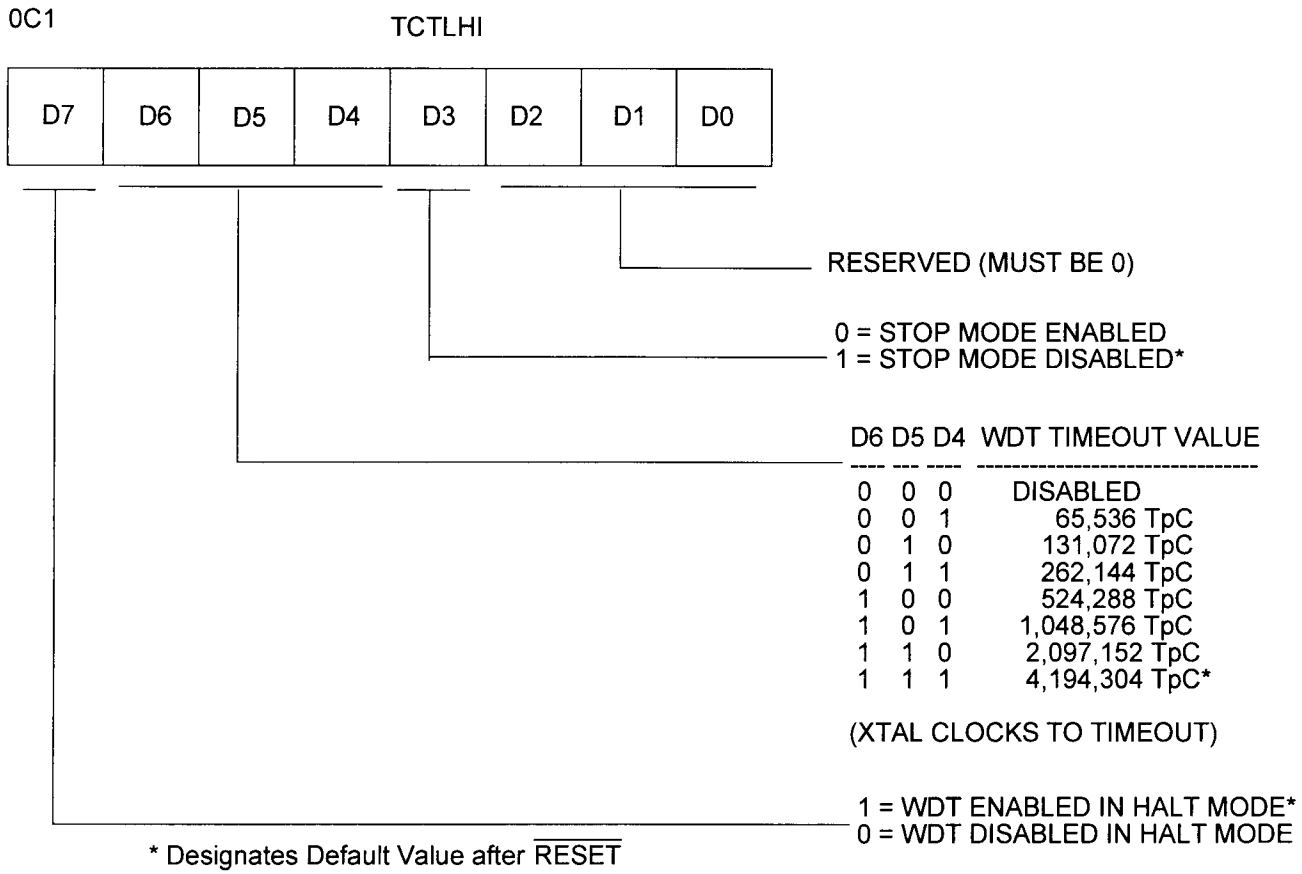


Figure 12. Z8E000 TCTLHI Register for Control of WDT

Note: The WDT can only be disabled via software if the first instruction out of RESET performs this function. Logic within the Z8E000 will detect that it is in the process of executing the first instruction after the part leaves RESET. During the execution of this instruction, the upper five bits of the TCTLHI register can be written. After this first instruction, hardware will not allow the upper five bits of this register to be written.

The TCTLHI bits for control of the WDT are described below:

WDT Time Select (D6, D5, D4). Bits 6, 5, and 4 determine the time-out period. Table 7 indicates the range of timeout values that can be obtained. The default values of D6, D5, and D4 are all 1, thus setting the WDT to its maximum timeout period when coming out of RESET.

Table 7. Time-Out Period of the WDT

D6	D5	D4	Crystal Clocks to Timeout	Time-Out Using a10 MHz Crystal
0	0	0	Disabled	Disabled
0	0	1	65,536 TpC	6.55 ms
0	1	0	131,072 TpC	13.11 ms
0	1	1	262,144 TpC	26.21 ms
1	0	0	524,288 TpC	52.43 ms
1	0	1	1,048,576 TpC	104.86 ms
1	1	0	2,097,152 TpC	209.72 ms
1	1	1	4,194,304 TpC	419.43 ms

Notes:
TpC = XTAL clock cycle.
The default on reset is D6 = D5 = D4 = 1.

OSCILLATOR OPERATION

The Z8E000 MCU uses a Pierce oscillator with an internal feedback circuit (Figure 14). The advantages of this circuit are low cost, large output signal, low power level in the crystal, stability with respect to V_{CC} and temperature, and low impedances (not disturbed by stray effects).

One draw back to the oscillator is the requirement for high gain in the amplifier to compensate for feedback path losses. The oscillator amplifies its own noise at start-up until it settles at the frequency that satisfies the gain/phase requirements ($A \times B = 1$, where $A = V_o/V_i$ is the gain of the amplifier and $B = V_i/V_o$ is the gain of the feedback element). The total phase shift around the loop is forced to zero (360 degrees). VIN must be in phase with itself. The amplifier/inverter thereby provides a 180-degree phase shift, forcing the feedback element to provide the other 180 degrees of phase shift.

R_I is a resistive component placed from output to input of the amplifier. The purpose of this feedback is to bias the amplifier in its linear region and to provide the start-up transition.

Capacitor C_2, combined with the amplifier output resistance, provides a small phase shift. It will also provide some attenuation of overtones.

Capacitor C_1, combined with the crystal resistance, provides additional phase shift.

C_1 and C_2 can affect the start-up time if they increase dramatically in size. As C_1 and C_2 increase, the start-up time increases until the oscillator reaches a point where it does not start up any more.

It is recommended for fast and reliable oscillator start-up (over the manufacturing process range) that the load capacitors be sized as low as possible without resulting in overtone operation.

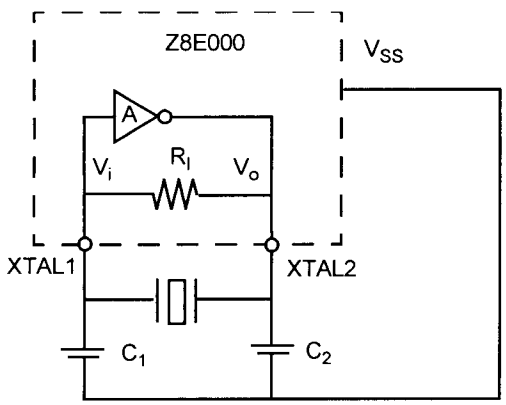


Figure 14. Pierce Oscillator with Internal Feedback Circuit

Layout

Traces connecting crystal, caps, and the Z8E000 oscillator pins should be as short and wide as possible, to reduce parasitic inductance and resistance. The components (caps, crystal, resistors) should be placed as close as possible to the oscillator pins of the Z8E000.

The traces from the oscillator pins of the IC and the ground side of the lead caps should be guarded from all other traces (clock, V_{CC}, address/data lines, system ground) to reduce cross talk and noise injection. Guarding is usually accomplished by keeping other traces and system ground trace planes away from the oscillator circuit, and by placing a Z8E000 device V_{SS} ground ring around the traces/components. The ground side of the oscillator lead caps should be connected to a single trace of the Z8E000 V_{SS} (GND) pin. The ground side of these caps should not be shared with any other system ground trace or components except at the Z8E000 device V_{SS} pin. The objective is to prevent differential system ground noise injection into the oscillator (Figure 15).

Indications of an Unreliable Design

There are two major indicators that are used in working designs to determine their reliability over full lot and temperature variations. They are:

Start-up Time. If start-up time is excessive, or varies widely from unit to unit, there is probably a gain problem. C_1 and C_2 require reduction if the amplifier gain is not adequate at frequency, or crystal R's are too large.

Output Level. The signal at the amplifier output should swing from ground to V_{CC} to indicate adequate gain in the amplifier. As the oscillator starts up, the signal amplitude grows until clipping occurs. At this point, the loop gain is effectively reduced to unity, and constant oscillation is achieved. A signal of less than 2.5 volts peak-to-peak is an indication that low gain can be a problem. Either C_1 or C_2 should be made smaller or a low-resistance crystal should be used.

Circuit Board Design Rules

The following circuit board design rules are suggested:

- To prevent induced noise, the crystal and load capacitors should be physically located as close to the Z8E000 as possible.
- Signal lines should not run parallel to the clock oscillator inputs. In particular, the crystal input circuitry and the internal system clock output should be separated as much as possible.

TIMERS (Continued)

er, when hardware clears a control register bit for a timer that is configured for single-shot operation, the clearing of the control bit will override a software write. Reading either register can be done at any time, and will have no effect on the functionality of the timer.

When defined to operate as a single 16-bit entity, the entire 16-bit value must reach 0 before an interrupt is generated. In this case, a single interrupt will be generated, and the interrupt will correspond to the even 8-bit timer. For example, timers T2 and T3 are cascaded to form a single 16-bit timer, so the interrupt for the combined timer will be defined to be that of timer T2 rather than T3 (Figure 20). When a timer pair is specified to act as a single 16-bit timer, the even timer registers in the pair (timer T2) will be defined to hold the timer's least significant byte. Conversely, the odd timer in the pair (timer T3) will hold the timer's most significant byte.

In parallel with the posting of the interrupt request, the interrupting timer's count value will be initialized by copying the contents of the auto-initialization value register to the count value register.

Note: Any time that a timer pair is defined to act as a single 16-bit timer, the auto-reload function will be performed automatically. All 16-bit timers will continue counting while their interrupt requests are active, and will operate in a free-running manner.

If interrupts are disabled for a long period of time, it is possible for the timer to decrement to 0 again before its initial interrupt has been responded to. This condition is termed a degenerate case, and hardware is not required to detect it.

When the timer control register is written, all timers that are enabled by the write will begin counting using the value that is held in their count register. In this case, an auto-initialization is not performed. All timers can receive an internal clock source only. Each timer that is enabled will be updated every 8th XTAL clock cycle.

RESET CONDITIONS

After a hardware $\overline{\text{RESET}}$, the timers are disabled. See Table 5 for timer control, value, and auto-initialization register status after $\overline{\text{RESET}}$.

I/O PORTS

The Z8E000 has 13 lines dedicated to input and output. These lines are grouped into two ports known as Port A and Port B. Port A is an 8-bit port that is bit-programmable as either inputs or outputs. Port B can be programmed to provide standard input/output or the following special functions: SMR input and external interrupt inputs.

All ports have push-pull CMOS outputs. In addition, the outputs of Port A, on a bit-wise basis, can be configured for open-drain operation. As such, the register values for "/" at a given bit position only affect the bit in question.

Each port is defined by a set of four control registers. See Figure 21.

Directional Control and Special Function Registers

Each port on the Z8E000 has an associated and dedicated Directional Control Register that determines on a bit-wise basis whether a given port bit will operate as an input or as an output.

Each port on the Z8E000 has a Special Function Register that, in conjunction with the directional control register, implements on a bit-wise basis, and supports special functionality that can be defined for each particular port bit.

Input and Output Value Registers

Each port has an Output Value Register and an Input Value Register. For port bits configured as an input by means of the Directional Control Register, the Input Value Register for that bit position will contain the current synchronized input value.

REGISTER	ADDRESS	IDENTIFIER
Port B SPECIAL FUNCTION	0D7H	PTBSFR
Port B DIRECTIONAL CONTROL	0D6H	PTBDIR
Port B OUTPUT VALUE	0D5H	PTBOUT
Port B INPUT VALUE	0D4H	PTBIN
Port A SPECIAL FUNCTION	0D3H	PTASFR
Port A DIRECTIONAL CONTROL	0D2H	PTADIR
Port A OUTPUT VALUE	0D1H	PTAOUT
Port A INPUT VALUE	0D0H	PTAIN

Figure 21. Z8E000 I/O Ports Registers

For port bits configured as an output by means of the Directional Control Register, the value held in the corresponding bit of the Output Value Register is driven directly onto the output pin. The opposite register bit for a given pin (the output register bit for an input pin and the input register bit for an output pin) will hold their previous value. They will not be changed by hardware nor will they have any effect on the hardware.

PORT A

Port A is a general-purpose port (Figure 23). Each of its lines can be independently programmed as input or output via the Port A Directional Control Register (PTADIR at 0D2H) as seen in Figure 22. A bit set to a "1" in PTADIR configures the corresponding bit in Port A as an output, while a bit cleared to "0" configures the corresponding bit in Port A as an input.

The input buffers are Schmitt-triggered. Bits programmed as outputs can be individually programmed as either push-pull or open drain by setting the corresponding bit in the Special Function Register (PTASFR, Figure 27.)

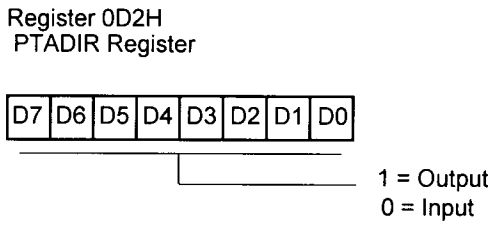


Figure 22. Port A Directional Control Register

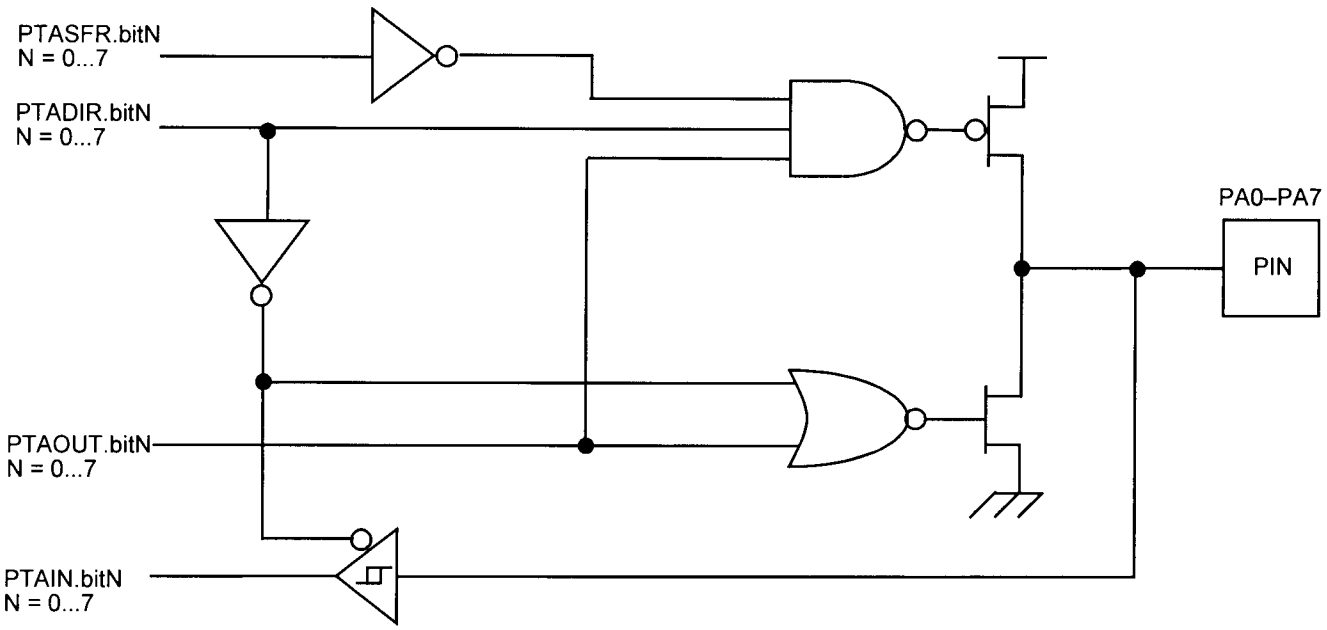


Figure 23. Port A Configuration with Open-Drain Capability and Schmitt-Trigger

PORT B

Port B Description

Port B is a 5-bit, bidirectional, CMOS-compatible I/O port. These five I/O lines can be configured under software control to be an input or output, independently. Input buffers are Schmitt-triggered. See Figure 29 through Figure 33 for diagrams of all five Port B pins.

In addition to standard input/output capability on all five pins of Port B, each pin provides special functionality as indicated in Table 8:

Table 8. Port B Special Functions

Port Pin	Input Special Function	Output Special Function
PB0	Stop Mode Recovery Input	None
PB1	None	None
PB2	IRQ3	None
PB3	None	None
PB4	IRQ1/IRQ4	None

Special functionality is invoked via the Port B Special Function Register. See Figure 28 for the arrangement and control conventions for this register.

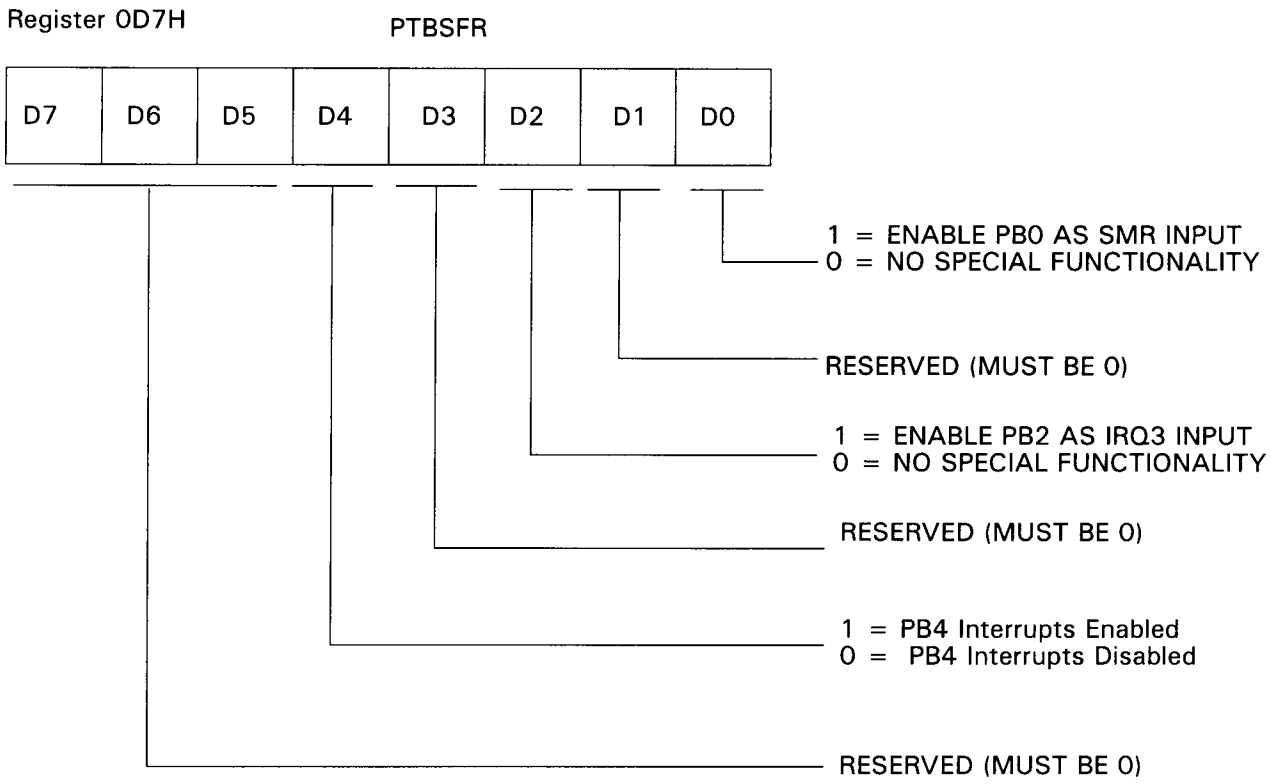


Figure 28. Port B Special Function Register

PORT B—PIN 0 CONFIGURATION

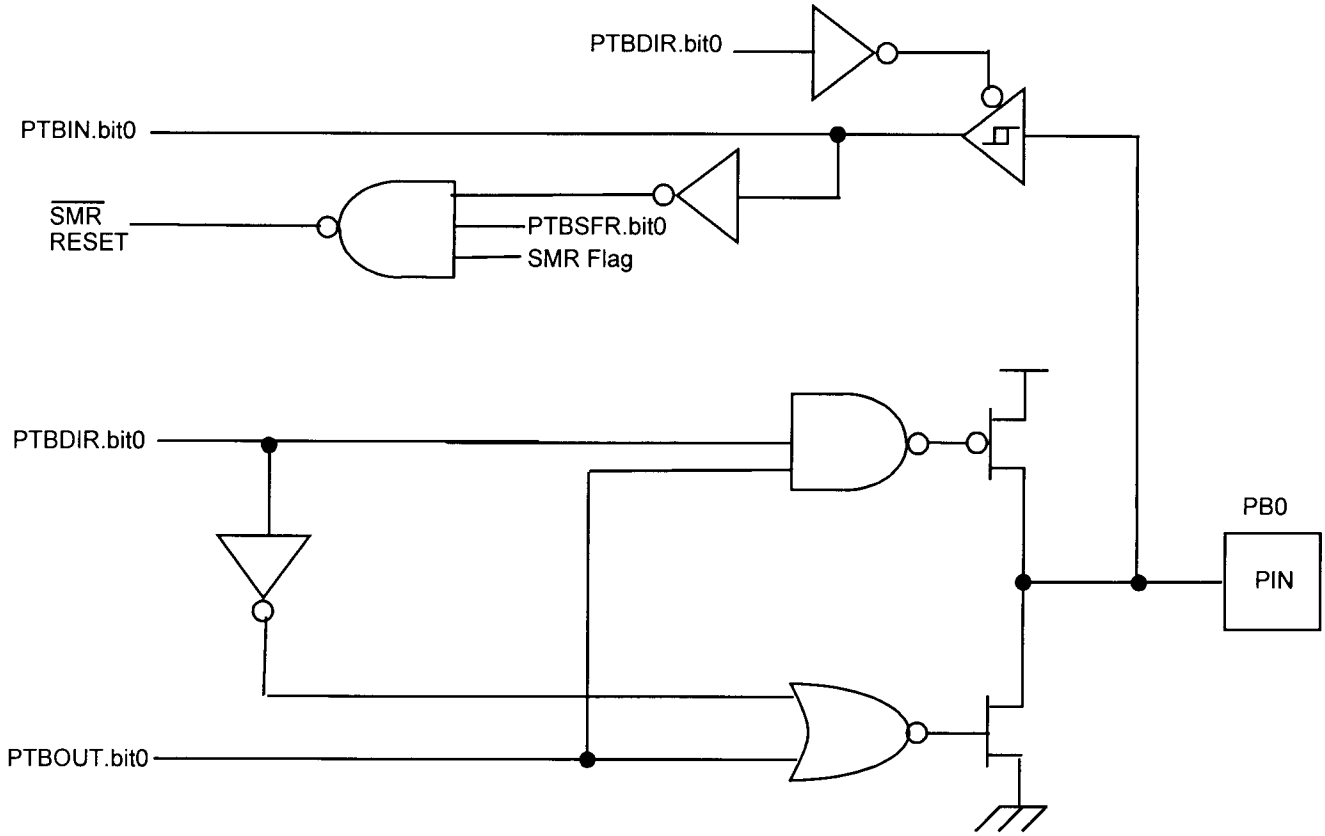


Figure 29. Port B Pin 0 Diagram

PORT B CONTROL REGISTER DEFINITIONS

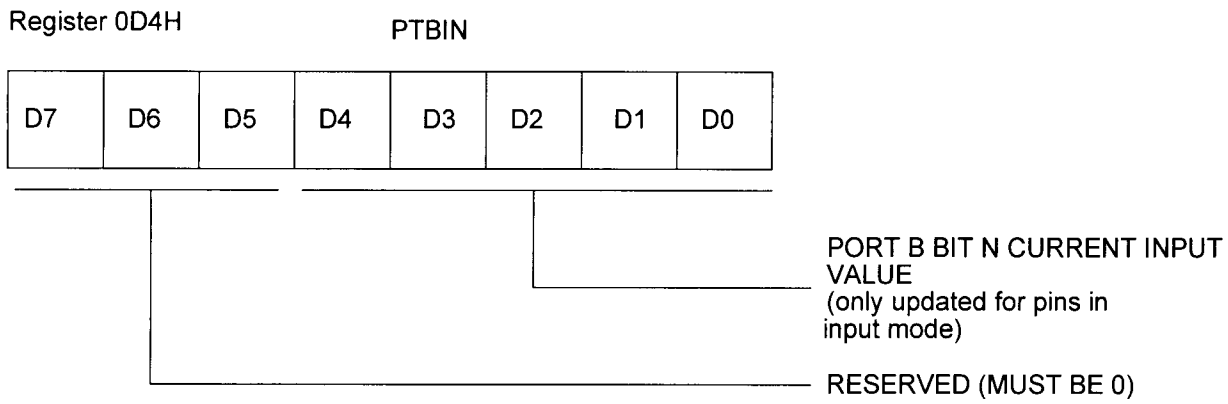


Figure 33. Port B Input Value Register

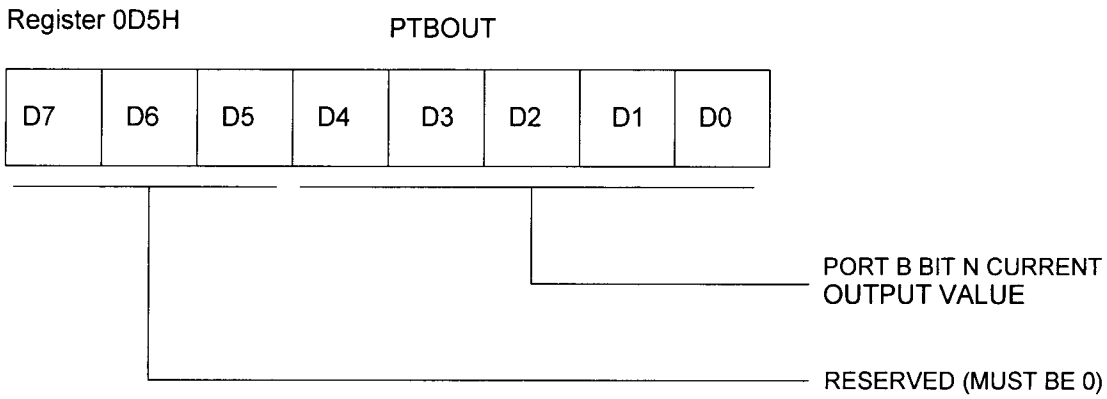


Figure 34. Port B Output Value Register

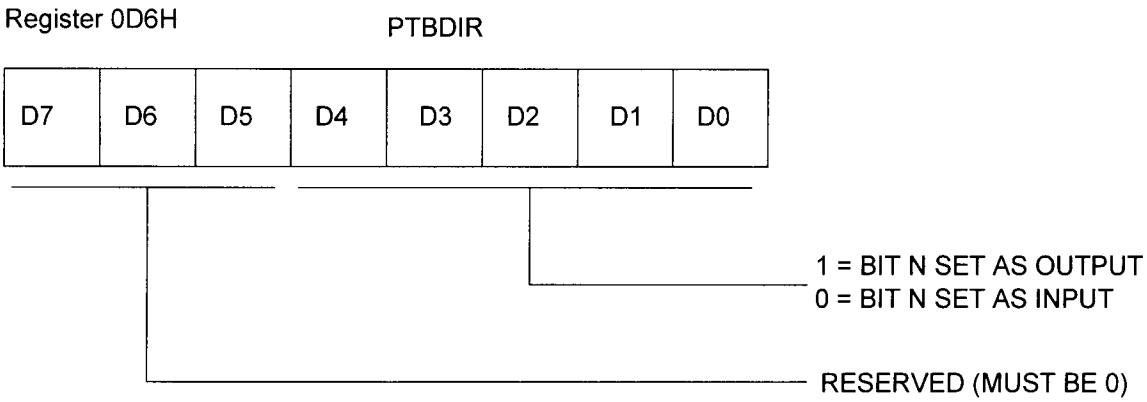


Figure 35. Port B Directional Control Register

I/O PORT RESET CONDITIONS

Full Reset

Port A and Port B output value registers are not affected by $\overline{\text{RESET}}$.

On $\overline{\text{RESET}}$, the Port A and Port B directional control registers will be cleared to all zeros, which will define all pins in both ports as inputs.

On $\overline{\text{RESET}}$, the directional control registers redefine all pins as inputs, and the Port A and Port B input value registers will overwrite the previously held data with the current sample of the input pins.

On $\overline{\text{RESET}}$, the Port A and Port B special function registers will be cleared to all zeros, which will deactivate all port special functions.

Note: The SMR and WDT timeout events are NOT full device resets. None of the port control registers is affected by either of these events.

INPUT PROTECTION

All I/O pins on the Z8E000 have diode input protection. There is a diode from the I/O pad to V_{CC} and to V_{SS}. See Figure 37.

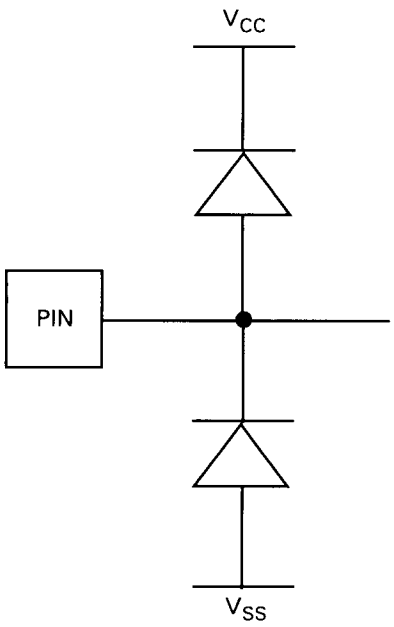


Figure 37. I/O Pin Diode Input Protection

However, on the Z8E000, the $\overline{\text{RESET}}$ pin has only the input protection diode from the pad to V_{SS}. See Figure 38.

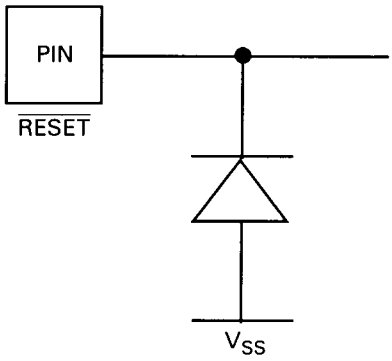
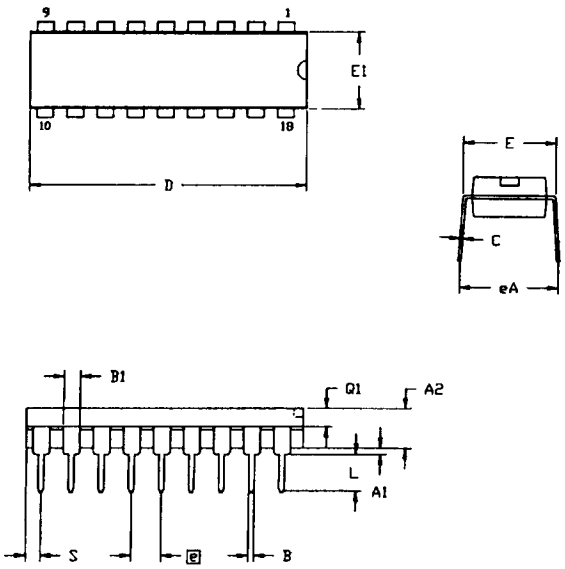


Figure 38. $\overline{\text{RESET}}$ Pin Input Protection

The High-side input protection diode was removed on this pin to allow the application of high voltage during the OTP programming mode.

For better noise immunity in applications that are exposed to system EMI, a clamping diode to V_{CC} from this pin is required to prevent entering the OTP programming mode, or to prevent high voltage from damaging this pin.

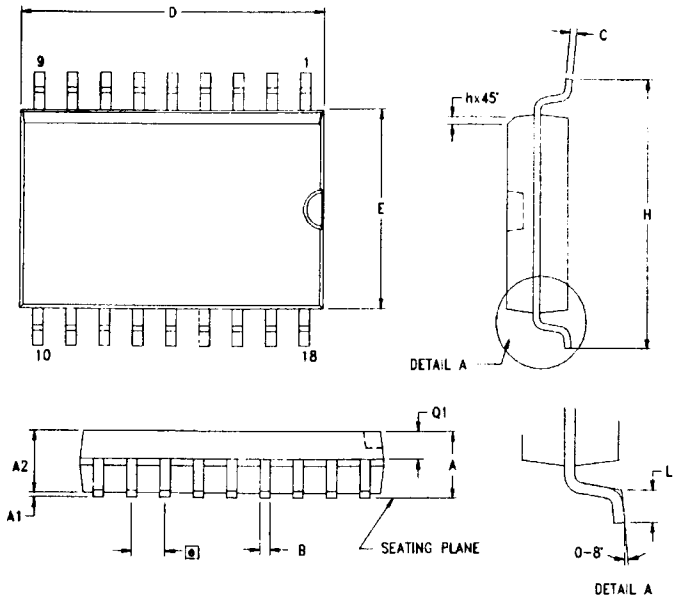
PACKAGE INFORMATION



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A1	0.51	0.81	.020	.032
A2	3.25	3.43	.128	.135
B	0.38	0.53	.015	.021
B1	1.14	1.65	.045	.065
C	0.23	0.38	.009	.015
D	22.35	23.37	.880	.920
E	7.62	8.13	.300	.320
E1	6.22	6.48	.245	.255
e	2.54 TYP		.100 TYP	
eA	7.87	8.89	.310	.350
L	3.18	3.81	.125	.150
Q1	1.52	1.65	.060	.065
S	0.89	1.65	.035	.065

CONTROLLING DIMENSIONS : INCH

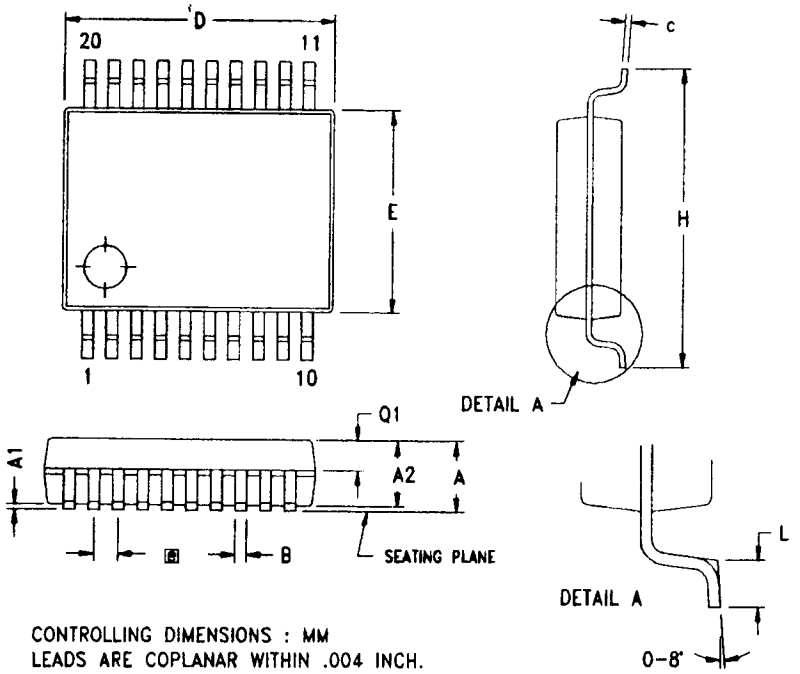
Figure 39. 18-Pin DIP Package Diagram



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A	2.40	2.65	0.094	0.104
A1	0.10	0.30	0.004	0.012
A2	2.24	2.44	0.088	0.096
B	0.36	0.46	0.014	0.018
C	0.23	0.30	0.009	0.012
D	11.40	11.75	0.449	0.463
E	7.40	7.60	0.291	0.299
e	1.27 TYP		0.050 TYP	
H	10.00	10.65	0.394	0.419
h	0.30	0.50	0.012	0.020
L	0.60	1.00	0.024	0.039
Q1	0.97	1.07	0.038	0.042

CONTROLLING DIMENSIONS : MM
LEADS ARE COPLANAR WITHIN .004 INCH.

Figure 40. 18-Pin SOIC Package Diagram



SYMBOL	MILLIMETER			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.73	1.85	1.98	0.068	0.073	0.078
A1	0.05	0.13	0.21	0.002	0.005	0.008
A2	1.68	1.73	1.83	0.066	0.068	0.072
B	0.25	0.30	0.38	0.010	0.012	0.015
C	0.13	0.15	0.22	0.005	0.006	0.009
D	7.07	7.20	7.33	0.278	0.283	0.289
E	5.20	5.30	5.38	0.205	0.209	0.212
e	0.65 TYP			0.0256 TYP		
H	7.65	7.80	7.90	0.301	0.307	0.311
L	0.56	0.75	0.94	0.022	0.030	0.037
Q1	0.74	0.78	0.82	0.029	0.031	0.032

Figure 41. 20-Pin SSOP Package Diagram

ORDERING INFORMATION

Standard Temperature		
18-Pin DIP	**18-Pin SOIC**	**20-Pin SSOP**
Z8E00010PSC	Z8E00010SSC	Z8E00010HSC

Extended Temperature		
18-Pin DIP	**18-Pin SOIC**	**20-Pin SSOP**
Z8E00010PEC	Z8E00010SEC	Z8E00010HEC

For fast results, contact your local ZiLOG sales office for assistance in ordering the part(s) required.

Codes	
Preferred Package	P = Plastic DIP
Longer Lead Time	S = SOIC
	H = SSOP
Preferred Temperature	S = 0°C to +70°C
	E = –40°C to +105°C
Speed	10 = 10 MHz
Environmental	C = Plastic Standard

Example:

Z 8E000 10 P S C is a Z86E000, 10 MHz, DIP, 0° to +70°C, Plastic Standard Flow